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*The Institute for  
Interconnecting  
and Packaging  
Electronic Circuits*

# IPC-DW-426

## Specifications for Assembly of Discrete Wiring

**ANSI/IPC-DW-426**

A standard developed by the Institute for Interconnecting  
and Packaging Electronic Circuits

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## Table of Contents

<b>1.0</b>	<b>SCOPE</b> .....	1			
1.1	Scope .....	1	3.5.1	Part Location.....	3
1.2	Classification .....	1	3.5.2	Conductive Areas.....	3
1.2.1	Types .....	1	3.5.3	Part Spacing .....	3
<b>2.0</b>	<b>APPLICABLE DOCUMENTS</b> .....	<b>1</b>	3.5.4	Alignment of Parts Leads.....	3
2.1	Industrial Documents.....	1	3.5.5	Stress Relief Bends.....	4
2.1.1	IPC .....	1	3.5.6	Lead Formation.....	4
2.1.2	ASTM .....	1	3.5.7	Axial Leaded Parts .....	5
2.2	Government Documents .....	1	3.5.8	Non Axial-Leaded Parts and Multiple Leaded Components.....	6
2.2.1	Military Specifications .....	1	3.5.9	Part Attachment.....	7
2.2	Military Standards .....	1	3.6	Interconnection Techniques .....	7
2.2.3	Federal .....	2	3.6.1	Soldering .....	7
<b>3.0</b>	<b>REQUIREMENTS</b> .....	<b>2</b>	3.6.2	Welding .....	7
3.1	General Requirements.....	2	3.6.3	Insulation Displacement .....	7
3.1.1	Conflict.....	2	3.6.4	Solderless .....	7
3.2	Qualification.....	2	3.7	Conformal Coating .....	7
3.2.1	First Article .....	2	3.7.1	Coating Area .....	7
3.3	Terms and Definitions.....	2	3.7.2	Adjustable Components.....	7
3.3.1	Automated Component Insertion .....	2	3.7.3	Mating Surfaces .....	7
3.3.2	Buffer Material.....	2	3.7.4	Masking.....	7
3.3.3	Clinched Lead.....	2	3.7.5	Compatibility.....	7
3.3.4	Component .....	2	3.7.6	Thickness.....	7
3.3.5	Component Mounting.....	2	3.7.7	Electrical Performance.....	7
3.3.6	Component Orientation.....	2	3.7.8	Buffer Material.....	7
3.3.7	Cracking .....	2	3.7.9	Surfaces to be Free of Coating .....	7
3.3.8	Discrete Wiring Assembly.....	2	3.7.10	Cleanliness .....	7
3.3.9	Discrete Wiring Board.....	2	3.8	Rework, Repair and Modification .....	8
3.3.10	Hard Wiring .....	2	3.8.1	Rework .....	8
3.3.11	Jumper Wire.....	2	3.8.2	Repairs.....	8
3.3.12	Modifications.....	2	3.8.3	Modifications.....	8
3.3.13	Partially Clinched Lead.....	2	3.9	Assembly Performance Requirements .....	8
3.3.14	Repair .....	2	3.9.1	Bow and Twist.....	8
3.3.15	Rework .....	2	3.9.2	Electrical Parameters .....	8
3.3.16	Straight-Through Lead.....	3	3.9.3	Vibration (when specified) .....	8
3.4	Material .....	3	3.9.4	Shock (when specified).....	8
3.4.1	Materials and Process Compatibility .....	3	3.9.5	Thermal Shock (when specified).....	8
3.4.2	Discrete Wiring Boards .....	3	3.9.6	Temperature-Altitude (when specified).....	8
3.4.3	Component Leads and Wires .....	3	3.9.7	Humidity (when specified) .....	8
3.4.3.1	Component Parts and Wires .....	3	3.9.8	Salt Fog (when specified).....	8
3.4.4	Solder .....	3	3.9.9	Fungus (when specified).....	8
3.4.5	Soldering Flux.....	3	3.10	Markings .....	8
3.4.6	Conformal Coating .....	3	3.11	Workmanship .....	8
3.4.7	Buffer Material.....	3	<b>4.0</b>	<b>QUALITY ASSURANCE PROVISIONS</b> .....	<b>9</b>
3.4.8	Hard Wires (Jumper, Jumper Wires).....	3	4.1	Responsibility for Inspection.....	9
3.5	Design Principles and Production Criteria.....	3	4.1.1	Test Equipment Inspection Facilities .....	9
			4.1.2	Inspection Conditions .....	9

4.2 Levels of Inspection ..... 9

4.3 Incoming Component and Material Inspection ..... 9

4.3.1 Solderability of Component Leads and Wires (excludes parts not intended to be soldered)..... 9

4.4 First Article Inspection ..... 9

4.4.1 Inspection Routine ..... 9

4.4.2 Failures..... 9

4.4.3 First Article Approval ..... 10

4.5 In-Process Inspection..... 10

4.5.1 Soldered Connections Inspection ..... 10

4.5.2 Inspection Lot for Cleanliness..... 11

4.5.3 Failures..... 11

4.5.4 Rejected Lots ..... 11

4.6 Quality Conformance Inspection ..... 11

4.6.1 Inspection of Discrete Wiring Assemblies for Delivery ..... 11

4.7 Methods of Examination and Test ..... 11

4.7.1 Visual and Dimensional Examination ..... 11

4.7.2 Preparation of Solvent Extract Test Solution ... 13

4.7.3 Bow and Twist (See 3.9.1) ..... 13

4.7.4 Electrical Parameter (See 3.9.2)..... 13

4.7.5 Vibration (See 3.9.3)..... 13

4.7.6 Shock (See 3.9.4)..... 14

4.7.7 Thermal Shock (See 3.9.5)..... 14

4.7.8 Temperature-Altitude (See 3.9.6)..... 14

4.7.9 Humidity (3.9.7) ..... 14

4.7.10 Salt Fog (3.9.8)..... 14

4.7.11 Fungus (See 3.9.9)..... 14

4.8 Inspection of Packaging ..... 14

**5.0 PREPARATION FOR DELIVERY** ..... 14

5.1 ..... 14

**6.0 NOTES** ..... 14

6.1 Ordering Data ..... 14

6.2 Flux Removal..... 14

6.3 Plastic Bags..... 14

6.4 Alternative Methods ..... 14

6.5 Ultrasonic Cleaning ..... 14

6.6 Sensitive-Component Handling..... 15

**APPENDIX** ..... 16

**10.0 SCOPE** ..... 16

10.1 Purpose..... 16

10.2 Authorization..... 16

**20.0 GENERAL** ..... 16

20.1 Quality..... 16

20.2 Performance ..... 16

20.3 Documentation of Standard Repair ..... 16

20.4 Quality Assurance Provisions..... 16

20.5 Materials..... 16

20.5.1 Solder ..... 16

20.5.2 Soldering Flux..... 16

20.5.3 Adhesive..... 16

20.5.4 Conformal Coating ..... 16

20.5.5 Hook-Up-Wire ..... 16

20.5.6 Insulation Tubing ..... 16

20.6 Component Replacement..... 16

20.7 Workmanship ..... 17

**30.0 DETAIL REQUIREMENTS** ..... 17

30.1 Standard Repairs ..... 17

30.1.1 Jumper Wires ..... 17

**Figures**

Figure 1 Lead bend ..... 4

Figure 2 ..... 5

Figure 3 ..... 5

Figure 4 Solder in bend radius..... 6

Figure 5 Perpendicular part mounting ..... 6

Figure 6 Flatpack (two wires or leads attached) ..... 17

Figure 7 Flatpack (one wire or lead attached) ..... 17

Figure 8 Dip type component ..... 18

Figure 9 Connector tang..... 19

Figure 10 Positioning wiring on circuits..... 19

**Tables**

Table 1 ..... 1

Table 2 Conductor Spacing..... 4

Table 3 ..... 7

Table 4 Incoming Component & Material Inspection ..... 10

Table 5 First Article Inspection..... 10

Table 6 In-Process Inspection..... 10

Table 7 Group A Inspection ..... 11

Table 8 Group B Inspection..... 11

Table 9 Equivalence Factors..... 15

# Specifications for Assembly of Discrete Wiring

## 1.0 SCOPE

**1.1 Scope** This specification covers the acceptance and test requirements of conformally coated and nonconformally coated discrete wiring assemblies consisting of discrete wiring boards manufactured in accordance with IPC-DW-425 on which separately manufactured electrical and/or mechanical components are mounted

## 1.2 Classification

**1.2.1 Types** Discrete wiring assemblies shall be of the types shown in Table 1.

**Table 1**

Type	Connection
A1	Solderless Wrap
A2	Clip Termination
A3	Insulation Displacement
B1	Wrapped and Soldered
B2	Reflowed Solder
B3	Heat Shrinkage Solder
C1	Plated-Through Hole
C2	Welded Pin
C3	Welded Land

## 2.0 APPLICABLE DOCUMENTS

**2.1 Industrial Documents** Unless otherwise specified, the following documents, of the issue currently in effect form a part of this specification to the extent specified herein.

### 2.1.1 IPC<sup>1</sup>

**IPC-T-50** Terms and Definitions

**IPC-DW-425** Design and End Product Requirements for Discrete Wiring Boards

**IPC-A-600** Acceptability of Printed Wiring Boards

**IPC-A-610** Acceptability of Printed Wiring Board Assemblies (Guidelines For)

**IPC-R-700** Modification and Repair for Printed Boards and Assemblies

**IPC-TM-650** Test Methods Manual

**IPC-CM-770** Printed Board Component Mounting

**IPC-S-805** Solderability Tests for Component Leads and Terminations

**IPC-S-815** General Requirements for Soldering Electronic Interconnections

**IPC-SF-818** General Requirements for Electronic Soldering Fluxes

**IPC-CC-830** Qualification and Conformance of Electrical Insulating Compound for Printed Board Assemblies

**IPC-SM-840** Qualification and Performance of Permanent Polymer Coating (Solder Mask) for Printed Circuits

### 2.1.2 ASTM<sup>2</sup>

**ASTM B-33** Tinned, Soft or Annealed Copper Wire for Electrical Purposes

**2.2 Government Documents<sup>3</sup>** Unless otherwise specified, the following documents, of the issue currently in effect, form a part of this specification to the extent specified herein.

### 2.2.1 Military Specifications

**MIL-P-13949** Plastic Sheet, Laminated, Metal Clad (for Printed Wiring Boards), General Specifications for

**MIL-F-14256** Flux Soldering, Liquid (Rosin Base)

**MIL-I-22129** Insulation Tubing, Electrical, Polytetrafluoroethylene Nonrigid

**MIL-I-43553** Marking Inks

### 2.2 Military Standards

**MIL-STD-105** Sampling Procedures and Tables for Inspection by Attributes

**MIL-STD-202** Test Methods for Electronic and Electrical Component Parts

**MIL-STD-810** Environmental Test Methods

**MIL-STD-45662** Calibration Systems Requirements

1. Publication are available from the IPC, 2215 Sanders Road, Northbrook, IL 60062-6135

2. Applications for test copies should be addressed to: American Society for Testing and Materials, 1916 Race Street, Philadelphia, PA 19130

3. To obtain document, write Naval Publications and Forms Center, 5801 Tabor Road, Philadelphia, PA 19130